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**DGD2101** 

### HIGH-SIDE AND LOW-SIDE GATE DRIVER IN SO-8 (TYPE TH)

### **Description**

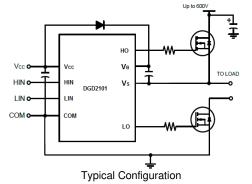
The DGD2101 is a high-voltage / high-speed gate driver capable of driving N-Channel MOSFETs and IGBTs in a high-side/low-side configuration. High-voltage processing techniques enable the DGD2101's high side to switch to 600V in a bootstrap operation. The 50ns (max) propagation delay matching between the high and the low side drivers allows high frequency switching.

The DGD2101 logic inputs are compatible with standard TTL and CMOS levels (down to 3.3V) for easy interfacing with controlling devices. The driver outputs feature high-pulse current buffers designed for minimum driver cross conduction. The low-side gate driver and logic share a common ground.

The DGD2101 is available in a space saving 8-pin SO (Type TH) package, the operating temperature extends from -40°C to +125°C.

### **Applications**

- DC-DC Converters
- DC-AC Inverters
- AC-DC Power Supplies
- Motor Controls
- Class D Power Amplifiers



#### **Features**

- Floating High-side Driver in Bootstrap Operation to 600V
- Drives Two N-Channel MOSFETs or IGBTs in High-side / Lowside Configuation
- Outputs Tolerant to Negative Transients
- Wide Low-side Gate Driver and Logic Supply: 10V to 20V
- Logic Inputs CMOS and TTL Compatible (Down to 3.3V)
- Schmitt Triggered Logic Inputs with Internal Pull Down
- Undervoltage Lockout for V<sub>CC</sub>
- Space Saving SO-8 (Type TH) Package Available
- Extended Temperature Range: -40°C to +125°C
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

### **Mechanical Data**

- Case: SO-8 (Type TH)
- Case Material: Molded Plastic. "Green" Molding Compound
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 <sup>®</sup>
- SO-8 Weight: 0.075 grams (Approximate)



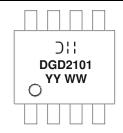
## Ordering Information (Note 4)

Ī	Part Number	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
	DGD2101S8-13	DGD2101	13	12	2,500

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

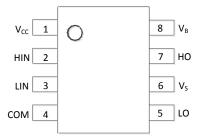
### **Marking Information**



Oll = Manufacturer's Marking
DGD2101 = Product Type Marking Code
YY = Year (ex: 16 = 2016)
WW = Week (01 - 53)



## **Pin Diagrams**

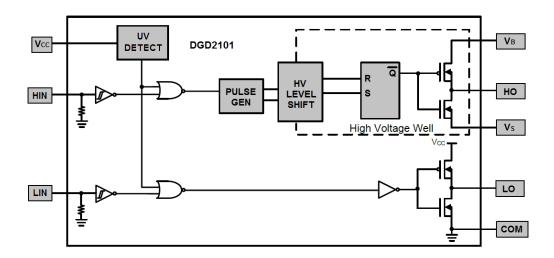


Top View: SO-8 (Type TH)

# **Pin Descriptions**

Pin Number	Pin Name	Function	
1	V <sub>CC</sub>	Low-side and logic fixed supply	
2	HIN	Logic input for high-side gate driver output (HO), in phase	
3	LIN	Logic input for low-side gate driver output (LO), in phase	
4	COM	Low-side return	
5	LO	Low-side gate drive output	
6	$V_S$	High-side floating supply return	
7	НО	High-side gate drive output	
8	$V_{B}$	High-side floating supply	

## **Functional Block Diagram**





## **Absolute Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
High-Side Floating Supply Voltage	V <sub>B</sub>	-0.3 to +624	V
High-Side Floating Supply Offset Voltage	Vs	V <sub>B</sub> -24 to V <sub>B</sub> +0.3	V
High-Side Floating Output Voltage	V <sub>HO</sub>	$V_S$ -0.3 to $V_B$ +0.3	V
Offset Supply Voltage Transient	dV <sub>S</sub> / dt	50	V/ns
Low-Side and Logic Fixed Supply Voltage	V <sub>CC</sub>	-0.3 to +24	V
Low-Side Output Voltage	V <sub>LO</sub>	-0.3 to V <sub>CC</sub> +0.3	V
Logic Input Voltage (HIN and LIN)	V <sub>IN</sub>	-0.3 to V <sub>CC</sub> +0.3	V

## Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor (Note 5)	$P_{D}$	0.625	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	200	°C/W
Thermal Resistance, Junction to Case (Note 5)	$R_{ heta JC}$	45	°C/W
Operating Temperature	$T_J$	+150	°C
Storage Temperature Range	T <sub>STG</sub>	-55 to +150	C

Note: 5. When mounted on a standard JEDEC 2-layer FR-4 board.

# **Recommended Operating Conditions**

Parameter	Symbol	Min	Max	Unit
High-Side Floating Supply Absolute Voltage	V <sub>B</sub>	V <sub>S</sub> + 10	V <sub>S</sub> + 20	V
High-Side Floating Supply Offset Voltage	Vs	(Note 6)	600	V
High-Side Floating Output Voltage	V <sub>HO</sub>	Vs	$V_{B}$	V
Low-Side and Logic Fixed Supply Voltage	V <sub>CC</sub>	10	20	V
Low-Side Output Voltage	V <sub>LO</sub>	0	V <sub>CC</sub>	V
Logic Input Voltage (HIN and LIN)	V <sub>IN</sub>	0	5	V
Ambient Temperature	T <sub>A</sub>	-40	+125	°C

Note: 6. Logic operation for  $V_S = -5V$  to +600V.



# DC Electrical Characteristics ( $V_{BIAS}$ ( $V_{CC}$ , $V_{BS}$ ) = 15V, @ $T_A$ = +25°C, unless otherwise specified.) (Note 7)

Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Logic "1" Input Voltage	V <sub>IH</sub>	2.5	-	-	V	V <sub>CC</sub> = 10V to 20V
Logic "0" Input Voltage	$V_{IL}$	_	-	0.8	V	$V_{CC} = 10V \text{ to } 20V$
High Level Output Voltage, V <sub>BIAS</sub> - V <sub>O</sub>	V <sub>OH</sub>	_	0.05	0.2	>	$I_O = 2mA$
Low Level Output Voltage, V <sub>O</sub>	V <sub>OL</sub>	_	0.02	0.1	V	$I_O = 2mA$
Offset Supply Leakage Current	I <sub>LK</sub>	_	-	50	μΑ	$V_B = V_S = 600V$
Quiescent V <sub>BS</sub> Supply Current	I <sub>BSQ</sub>	_	30	55	μΑ	V <sub>IN</sub> = 0V or 5V
Quiescent V <sub>CC</sub> Supply Current	Iccq	-	150	270	μΑ	V <sub>IN</sub> = 0V or 5V
Logic "1" Input Bias Current	I <sub>IN+</sub>	_	3.0	10	μΑ	$V_{IN} = 5V$
Logic "0" Input Bias Current	I <sub>IN-</sub>	-	_	5.0	μΑ	$V_{IN} = 0V$
V <sub>CC</sub> Supply Undervoltage Positive Going Threshold	V <sub>CCUV+</sub>	8.0	8.9	9.8	V	_
V <sub>CC</sub> Supply Undervoltage Negative Going Threshold	V <sub>CCUV-</sub>	7.4	8.2	9.0	V	_
Output High Short Circuit Pulsed Current	I <sub>O+</sub>	130	290	-	mA	V <sub>O</sub> = 0V, V <sub>IN</sub> = Logic"1", PW ≤ 10μs
Output Low Short Circuit Pulsed Current	I <sub>O-</sub>	270	600	_	mA	V <sub>O</sub> = 15V, V <sub>IN</sub> = Logic"0", PW ≤ 10μs

Note:

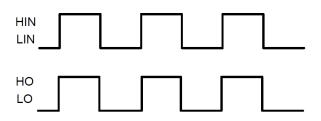
# $\textbf{AC Electrical Characteristics} \ (V_{BIAS} \ (V_{CC}, \ V_{BS}) = 15 \text{V}, \ C_L = 1000 \text{pF}, \ @T_A = +25 ^{\circ}\text{C}, \ unless otherwise specified.} )$

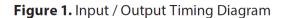
Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Turn-on Propagation Delay	t <sub>ON</sub>	-	160	220	ns	$V_S = 0V$
Turn-off Propagation Delay	toff	_	150	220	ns	V <sub>S</sub> = 600V
Turn-on Rise Time	t <sub>r</sub>	-	70	170	ns	_
Turn-off Fall Time	t <sub>f</sub>	_	35	90	ns	_
Delay Matching	t <sub>DM</sub>	-	-	50	ns	-

<sup>7.</sup> The V<sub>IN</sub> and I<sub>IN</sub> parameters are referenced to COM. The V<sub>O</sub> and I<sub>O</sub> parameters are referenced to COM and are applicable to the respective output pins: HO and LO.



# **Timing Waveforms**





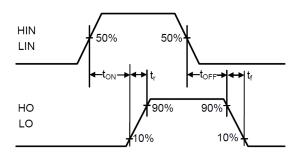


Figure 2. Switching Time Waveform Definitions

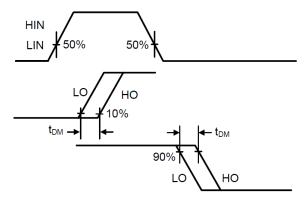


Figure 3. Delay Matching Waveform Definitions



## **Typical Performance Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

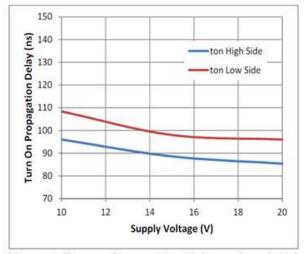


Figure 4. Turn-on Propagation Delay vs. Supply Voltage

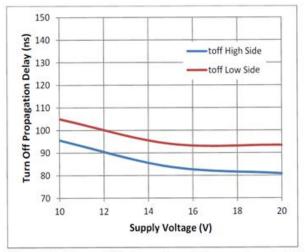


Figure 6. Turn-off Propagation Delay vs. Supply Voltage

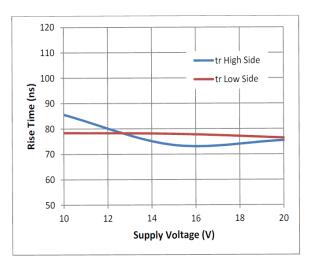


Figure 8. Rise Time vs. Supply Voltage

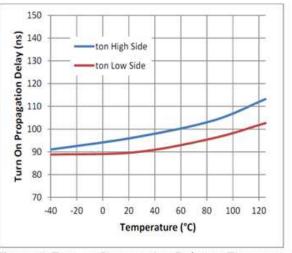


Figure 5. Turn-on Propagation Delay vs. Temperature

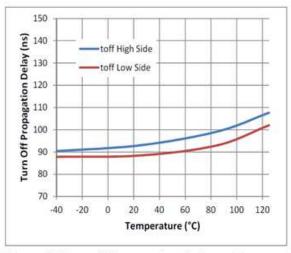


Figure 7. Turn-off Propagation Delay vs. Temperature

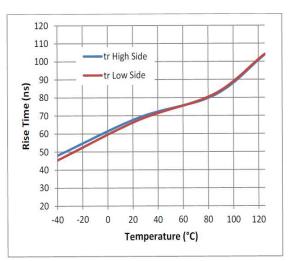


Figure 9. Rise Time vs. Temperature



## **Typical Performance Characteristics** (continued)

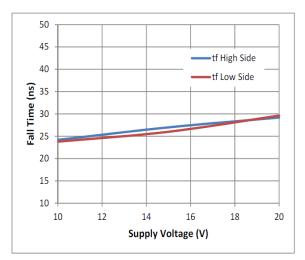


Figure 10. Fall Time vs. Supply Voltage

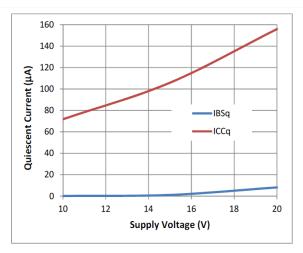


Figure 12. Quiescent Current vs. Supply Voltage

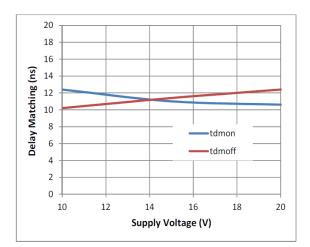


Figure 14. Delay Matching vs. Supply Voltage

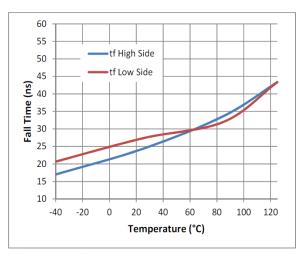


Figure 11. Fall Time vs. Temperature

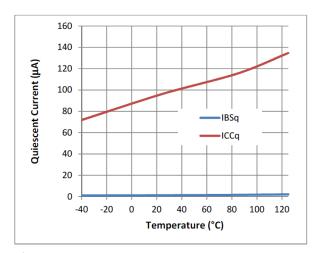


Figure 13. Quiescent Current vs. Temperature

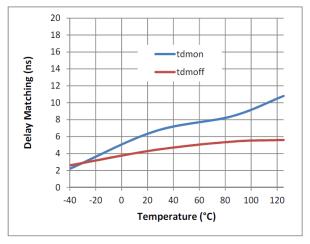


Figure 15. Delay Matching vs. Temperature



## **Typical Performance Characteristics (cont.)**

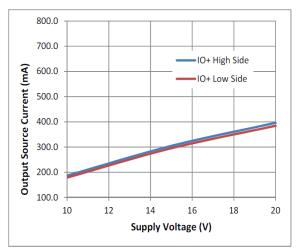


Figure 16. Output Source Current vs. Supply Voltage

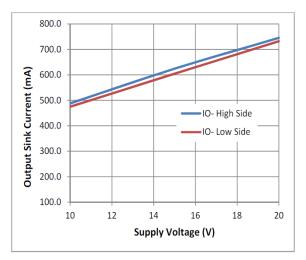


Figure 18. Output Sink Current vs. Supply Voltage

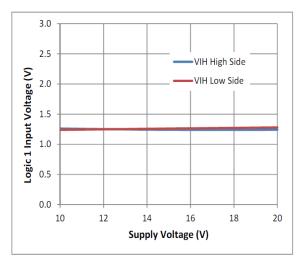


Figure 20. Logic 1 Input Voltage vs. Supply Voltage

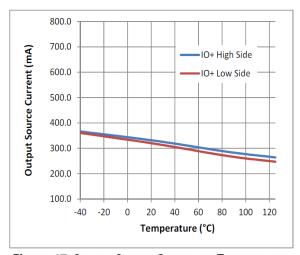


Figure 17. Output Source Current vs. Temperature

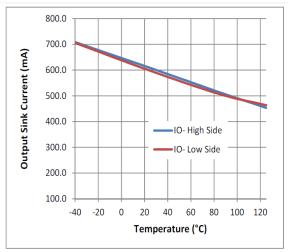


Figure 19. Output Sink Current vs. Temperature

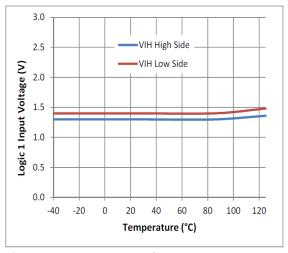


Figure 21. Logic 1 Input Voltage vs. Temperature



# **Typical Performance Characteristics** (cont.)

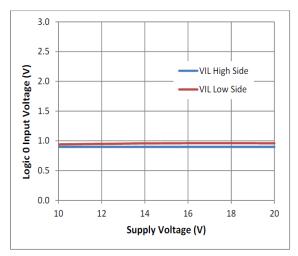
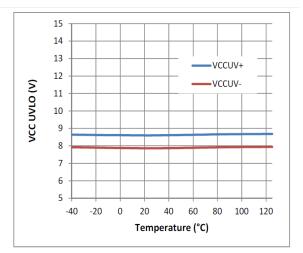


Figure 22. Logic 0 Input Voltage vs. Supply Voltage



**Figure 24.**  $V_{CC}$  UVLO vs. Temperature

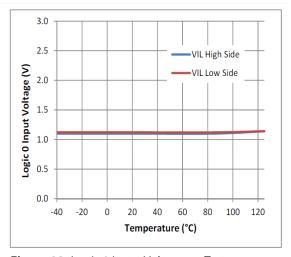


Figure 23. Logic 0 Input Voltage vs. Temperature

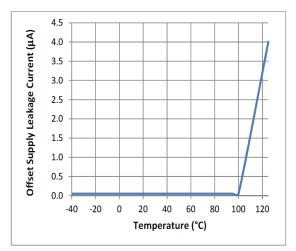


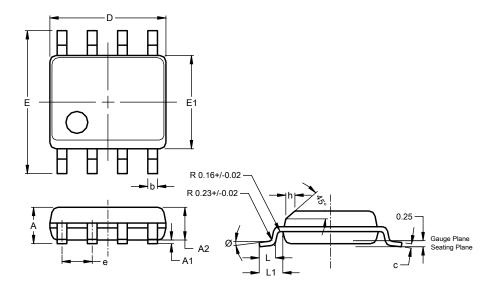
Figure 25. Offset Supply Leakage Current vs. Temperature



## **Package Outline Dimensions**

Please see AP02001 at http://www.diodes.com/\_files/datasheets/ap02001.pdf for the latest version.

### SO-8 (Type TH)

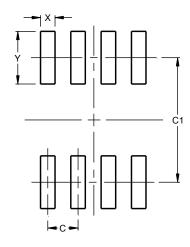


SO-8 (Type TH)						
Dim	Min	Max	Тур			
Α	1.35	1.75				
A1	0.10	0.25				
A2			1.45			
b	0.35	0.51				
С	0.190	0.248				
D	4.80	5.00	4.90			
Е	5.80	6.20	6.00			
E1	3.80	4.00	3.90			
е			1.27			
h	0.25	0.50				
L	0.41	1.27				
L1			1.04			
Ø	0°	8°				
All Dimensions in mm						

## **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/\_files/datasheets/ap02001.pdf for the latest version.

#### SO-8 (Type TH)



Dimensions	Value (in mm)
С	1.27
C1	5.20
Х	0.60
Υ	2.20

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.



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